



<b>Title of Change:</b>	Qualify ASE Kunshan as alternative assembly site for SOIC8.	
<b>Proposed first ship date:</b>	16 April 2019	
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Jack.Cartwright@onsemi.com>	
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Jacob.Saliba@onsemi.com>	
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>	
<b>Change Part Identification:</b>	Product marked with date code 1844 or later may be built from current factory or from OSPI Factory. The trace code marking on Line 2 is of the form ALYW where A = Assembly Location, L = Wafer Lot ID and YW is a 2-digit date code. Product marked with "AK" as the assembly location will be from ASEKS. Additionally on the label of the box and reel, the ASSY LOC: CV will also indicate product assembled in ASEKS. Please see sample label on Page 2 at the following URL <a href="http://www.onsemi.com/pub/Collateral/LABELRM-D.PDF">http://www.onsemi.com/pub/Collateral/LABELRM-D.PDF</a> to see the location of the ASSY LOC.	
<b>Change Category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
<b>Sites Affected:</b>	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: ASE Kunshan
<b>Description and Purpose:</b>  ON Semiconductor would like to inform its customers of the qualification of ASE Kunshan ASEKS for the assembly of SOIC-8 products listed in this Final Product Change Notification (FPCN). This is a capacity expansion, and at the end of the FPCN approval cycle, these products may be dual sourced from either ASEKS or from OSPI.  All products listed will continue to be tested at OSPI.  For assembly, BOM changes associated with this FPCN are shown here:		
	<b>OSPI</b>	<b>ASEKS</b>
Die Attach	CRM-1076WB, CRM-1191A	EN-4900GC
Mold Compound	G600	CEL9240
	<b>OSPI</b>	<b>ASEKS</b>
Product marking change	Assembly Location: P	Assembly Location: AK

**Reliability Data Summary:**

QV DEVICE NAME: NCP4303ADR2G

RMS: 048265

PACKAGE: SOIC-8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C, 100 % max rated Vcc	1008 hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/239
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL1 3x Reflow @ 260°C		0/640
RSH	JESD22- B106	Ta = 260C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 10 sec		0/45
PD	Physical Dimensions	Per Case Outline		0/30

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted by this change. Electrical Comparison reports are available upon request.

**List of Affected Parts:**

Part Number	Qualification Vehicle
NCP4303ADR2G	NCP4303ADR2G
NCP4303BDR2G	
NCP1611ADR2G	
NCP1611BDR2G	